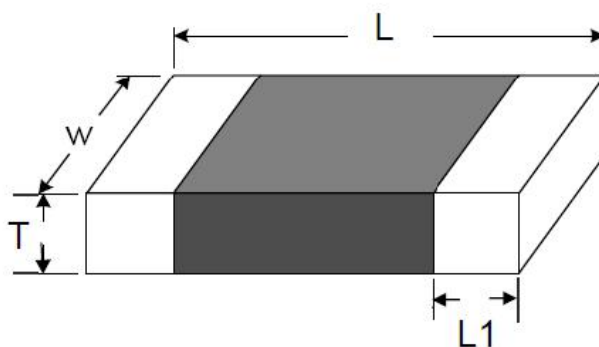


Chip NTC Thermistor

SN0201-X Series

Shape and Dimensions Unit: (mm)



Type	L	W	T	L1
Dimensions	0.6±0.05	0.3±0.05	0.3±0.05	0.15±0.05

Part Number Code

SN	0201	X	103	F	3435	F	A
(1)	(2)	(3)	(4)	(5)	(6)	(7)	(8)

- (1) SN: Socay Chip NTC Thermistor.
- (2) 0201: External Dimensions (L x W x T): 0.6mm x 0.30mm x 0.30mm.
- (3) X: Internal Code
- (4) 103: Nominal Zero-Power Resistance at 25°C: 222 = 2.2kΩ; 103 = 10kΩ; 474 = 470kΩ.
- (5) F: Tolerance of Resistance: F: ±1%; H: ±3%; J: ±5%.
- (6) 3435: B Constant: 3435 = 3435K; 3950 = 3950K; 4250 = 4250K.
- (7) F: Tolerance of B Constant: F: ±1%.
- (8) A: B Constant Calculation Method: A: 25°C & 85°C; B: 25°C & 50°C.

Chip NTC Thermistor

SN0201-X Series

Electrical Characteristics

1) F Series

Part Number	Resistance (25°C) (kΩ)	B Constant (25/50°C) (K)	B Constant (25/85°C) (K)	Dissipation Factor (mW/°C)	Thermal Time Constant (s)	Rated Electric Power (25°C) (mW)	Operating Ambient Temperature (°C)
SN0201X103F3435FA	10±1%	--	3435±1%	1	3	100	-40 ~ +125
SN0201X473F4050FB	47±1%	4050±1%	--	1	3	100	-40 ~ +125
SN0201X683F4150FB	68±1%	4150±1%	--	1	3	100	-40 ~ +125
SN0201X104F4250FB	100±1%	4250±1%	--	1	3	100	-40 ~ +125

2) H Series

Part Number	Resistance (25°C) (kΩ)	B Constant (25/50°C) (K)	B Constant (25/85°C) (K)	Dissipation Factor (mW/°C)	Thermal Time Constant (s)	Rated Electric Power (25°C) (mW)	Operating Ambient Temperature (°C)
SN0201X103H3435FA	10±3%	--	3435±1%	1	3	100	-40 ~ +125
SN0201X473H4050FB	47±3%	4050±1%	--	1	3	100	-40 ~ +125
SN0201X683H4150FB	68±3%	4150±1%	--	1	3	100	-40 ~ +125
SN0201X104H4250FB	100±3%	4250±1%	--	1	3	100	-40 ~ +125

3) J Series

Part Number	Resistance (25°C) (kΩ)	B Constant (25/50°C) (K)	B Constant (25/85°C) (K)	Dissipation Factor (mW/°C)	Thermal Time Constant (s)	Rated Electric Power (25°C) (mW)	Operating Ambient Temperature (°C)
SN0201X103J3435FA	10±5%	--	3435±1%	1	3	100	-40 ~ +125
SN0201X473J4050FB	47±5%	4050±1%	--	1	3	100	-40 ~ +125
SN0201X683J4150FB	68±5%	4150±1%	--	1	3	100	-40 ~ +125
SN0201X104J4250FB	100±5%	4250±1%	--	1	3	100	-40 ~ +125

Chip NTC Thermistor

SN0201-X Series

Test and Measurement Procedures

- ◆ Test Conditions:
Unless otherwise specified, the standard atmospheric conditions for measurement/test as:
 - a. Ambient Temperature: 25±2°C
 - b. Relative Humidity: 65±5%
 - c. Air Pressure: 86kPa to 106kPa

Storage Conditions of Products

- ◆ Storage Conditions:
Storage Temperature: -10°C ~ +40°C.
Relative Humidity: ≤ 75%RH.
Keep away from corrosive atmosphere and sunlight.
- ◆ Period of Storage: 6 months.

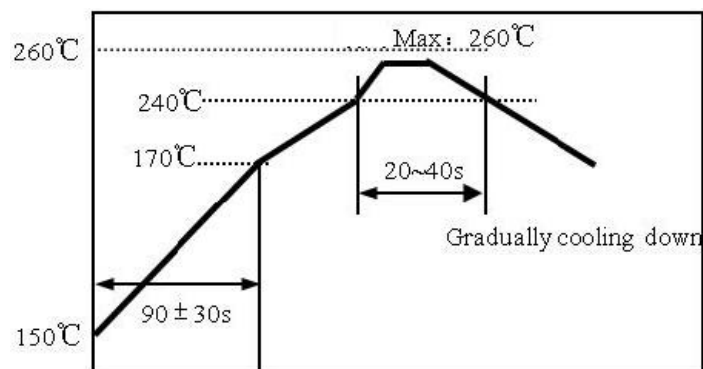
Reliability-SMD Type NTC Thermistor for Temperature Sensing

Test description	Standard	Test condition	Test requirement															
Bending strength	IEC 60068-2-21	Speed <0.5mm/sec Duration : 10sec on PCB Warp : 2mm	No visible damage $\Delta R_{25}/R_{25} \leq \pm 5\%$															
Solder ability	IEC 60068-2-58	245±5°C, 3±0.3 sec.	Above 95% in the terminal surface shall be with new solder															
Resistance to soldering heat	IEC 60068-2-58	260±5°C, 10±1 sec.	No visible damage $\Delta R_{25}/R_{25} \leq \pm 3\%$															
High temperature storage	IEC 60068-2-2	125±5°C, 1000±24 hrs.	No visible damage $\Delta R_{25}/R_{25} \leq \pm 5\%$															
Damp Heat, Steady State	IEC 60068-2-78	40±2°C, 90~95%RH, 1000±24 hrs.	No visible damage $\Delta R_{25}/R_{25} \leq \pm 3\%$															
Rapid Change of temperature	IEC 60068-2-14	Temperature cycle shall be repeated 5 cycles on PCB <table border="1" style="margin: 10px auto;"> <thead> <tr> <th>Step</th> <th>Temperature(°C)</th> <th>Period(minutes)</th> </tr> </thead> <tbody> <tr> <td>1</td> <td>-40±5</td> <td>30±3</td> </tr> <tr> <td>2</td> <td>Room temperature</td> <td>5±3</td> </tr> <tr> <td>3</td> <td>125±5</td> <td>30±3</td> </tr> <tr> <td>4</td> <td>Room temperature</td> <td>5±3</td> </tr> </tbody> </table>	Step	Temperature(°C)	Period(minutes)	1	-40±5	30±3	2	Room temperature	5±3	3	125±5	30±3	4	Room temperature	5±3	No visible damage $\Delta R_{25}/R_{25} \leq \pm 3\%$
Step	Temperature(°C)	Period(minutes)																
1	-40±5	30±3																
2	Room temperature	5±3																
3	125±5	30±3																
4	Room temperature	5±3																
Max. Power Dissipation	IEC 60539-14.26.3	25±5°C, Pmax, 1000±24 hrs.	No visible damage $\Delta R_{25}/R_{25} \leq \pm 5\%$															

Recommended Soldering Technologies

◆ Re-flowing Profile

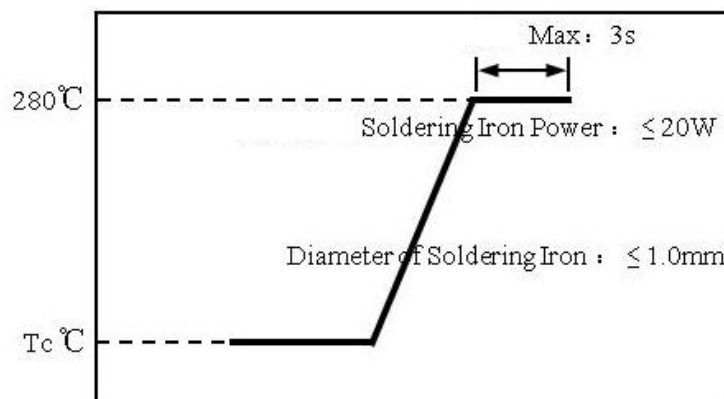
- (1) 1~2°C/sec. Ramp
- (2) Pre-heating: 150~170°C/90±30 sec.
- (3) Time above 240°C: 20~40 sec.
- (4) Peak temperature: 260°C Max./10 sec.
- (5) Solder paste: Sn/3.0Ag/0.5Cu
- (6) Max. 2 times for re-flowing



◆ Iron Soldering Profile

- (1) Iron soldering power: Max. 20W
- (2) Pre-heating: 150°C/60sec.
- (3) Soldering Tip temperature: 280°C Max.
- (4) Soldering time: 3 sec Max.
- (5) Solder paste: Sn/3.0Ag/0.5Cu
- (6) Max. 1 times for iron soldering

Note: Take care not to apply the tip of the soldering iron to the terminal electrodes.



Chip NTC Thermistor

SN0201-X Series

Packaging Information

Part Number	Packaging Option	Quantity
SN0201-X Series	Tape & Reel	15,000 PCS